



Dual N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
	11.5mΩ @ V _{GS} = 4.5V	10 A
20V	14mΩ @ V _{GS} = 2.5V	9 A

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(on)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

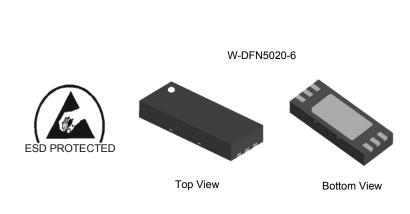
- General Purpose Interfacing Switch
- Power Management Functions

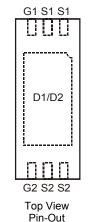
Features and Benefits

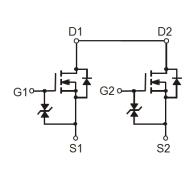
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: W-DFN5020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.03 grams (approximate)







Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2013UFX-7	W-DFN5020-6	3000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.htmlfor more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



FX = Product Type Marking Code YM = Date Code Marking Y = Year (ex: X = 2010) M = Month (ex: 9 = September)

Date Code Key

Date Code ite												
Year	201	0	2011		2012	20	13	2014		2015	2	2016
Code	X		Υ		Z	A	4	В		С		D
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteris	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	20	V		
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 5) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	ID	10 8	А
Continuous Drain Current (Note 5) V _{GS} = 2.5V	I _D	9 7	А		
Pulsed Drain Current (Note 7)	I _{DM}	80	Α		

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	P _D	0.78	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{\theta JA}$	163	°C/W
Power Dissipation (Note 6)	P _D	2.14	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	R ₀ JA	59	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

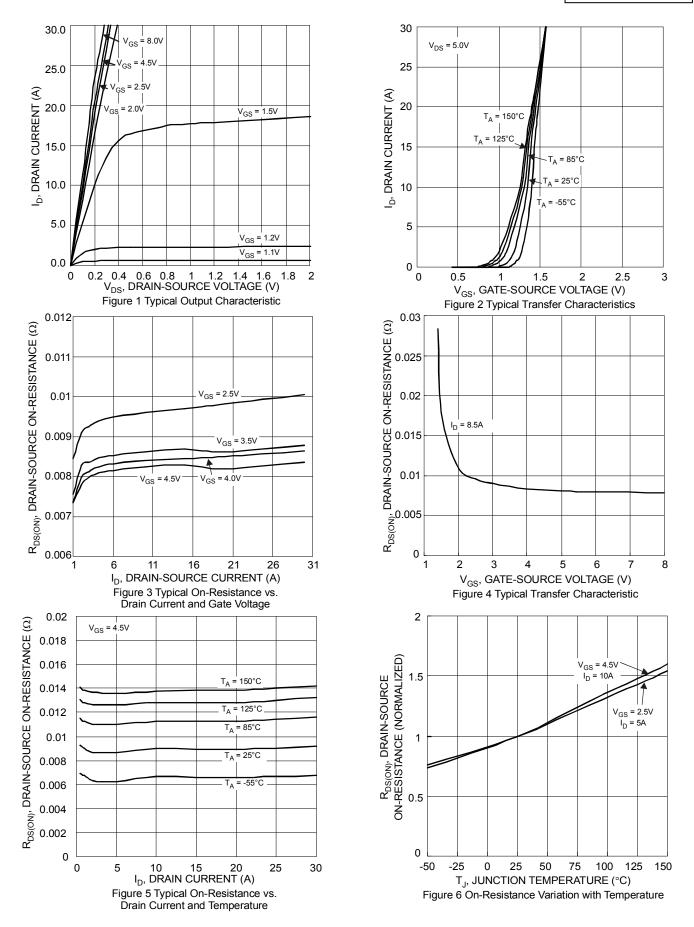
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
DFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_		V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	V _{DS} = 16V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_		±10	μΑ	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)						_	
Gate Threshold Voltage	V _{GS(th)}	0.5	_	1.1	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			8.4	11.5		$V_{GS} = 4.5V, I_D = 8.5A$	
			8.5	12.0		$V_{GS} = 4.0V, I_D = 8.5A$	
Static Drain-Source On-Resistance	R _{DS} (ON)	_	8.6	12.5	mΩ	$V_{GS} = 3.5V, I_D = 8.5A$	
	, ,		9.0	13.5		V _{GS} = 3.1V, I _D = 8A	
			9.6	14.0		V _{GS} = 2.5V, I _D = 8A	
Forward Transfer Admittance	Y _{fs}	_	18.2	_	S	V _{DS} = 5V, I _D = 4A	
Diode Forward Voltage	V _{SD}	_	_	1.2	V	V _{GS} = 0V, I _S = 8.5A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	_	2607		pF	101/1/	
Output Capacitance	Coss	_	255	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ -f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	236	_	pF	71 - 1.0WHZ	
Gate Resistance	Rq	_	1.2	_	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	32.4	_	nC		
Total Gate Charge (V _{GS} = 8V)	Qq	_	57.4	_	nC	7, 40,4 0.54	
Gate-Source Charge	Q _{as}	_	3.5	_	nC	$V_{DS} = 10V, I_D = 8.5A$	
Gate-Drain Charge	Q _{gd}	_	4.0	_	nC	7	
Turn-On Delay Time	t _{D(on)}	_	8.6	_	ns		
Turn-On Rise Time	tr	_	20.3	_	ns	V _{DS} = 10V, I _D = 8.5A	
Turn-Off Delay Time	t _{D(off)}	_	42.5	_	ns	$V_{GS} = 4.5V, R_G = 1.8\Omega$	
Turn-Off Fall Time	t _f	_	13.7	_	ns	7	

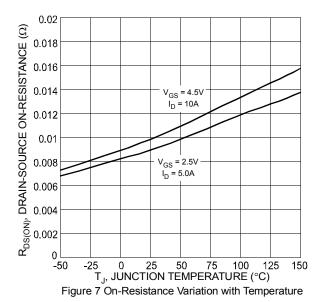
Notes:

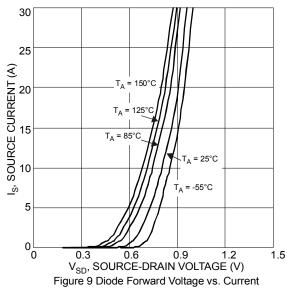
- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate
- 7. Repetitive rating, pulse width limited by junction temperature.
- Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.

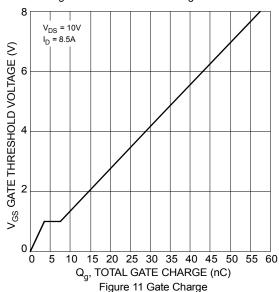


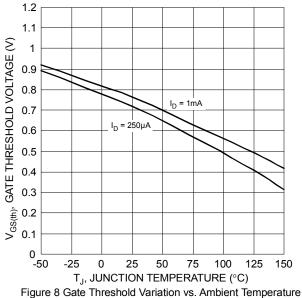


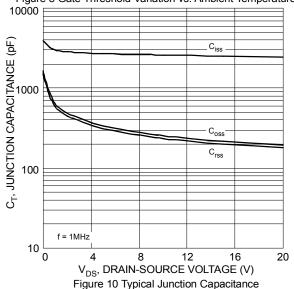








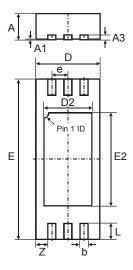






Package Outline Dimensions

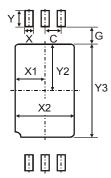
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



W-DFN5020-6							
Dim	Min	Max	Тур				
Α	0.75	0.85	0.80				
A1	0	0.05	0.02				
A3	-	-	0.15				
b	0.20	0.30	0.25				
D	1.90	2.10	2.00				
D2	1.40	1.60	1.50				
е	-	_	0.50				
Е	4.90	5.10	5.00				
E2	2.80	3.00	2.90				
٦	0.35	0.65	0.50				
Z	-	_	0.375				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.50
G	0.35
X	0.35
X1	0.90
X2	1.80
Υ	0.70
Y2	1.60
Y3	3.20



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